# SE8D30D, SE8D30G, SE8D30J

Vishay General Semiconductor

COMPLIANT

HALOGEN

FREE

### **Surface-Mount Standard Rectifier**



SlimSMAW (DO-221AD)

Cathode O Anode

#### **LINKS TO ADDITIONAL RESOURCES**



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	3 A			
$V_{RRM}$	200 V to 600 V			
I <sub>FSM</sub>	40 A			
$V_F$ at $I_F = 3 \text{ A (T}_J = 125 ^{\circ}\text{C)}$	0.86 V			
T <sub>J</sub> max.	175 °C			
Package	SlimSMAW (DO-221AD)			
Circuit configuration	Single			

#### **FEATURES**

- · Low-profile package
- Oxide planar chip junction
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
  - Automotive ordering code: base P/NHM3
- Compatible to SOD-128 package case outline
- Material categorization: for definitions of compliance please see <a href="https://www.vishay.com/doc?99912"><u>www.vishay.com/doc?99912</u></a>

#### TYPICAL APPLICATIONS

General purpose, power line polarity protection and rail-to-rail protection in consumer, industrial, and automotive applications.

#### **MECHANICAL DATA**

Case: SlimSMAW (DO-221AD)

Molding compound meets UL 94 V-0 flammability rating

Base P/N-M3 - halogen-free, RoHS-compliant Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

MAXIMUM RATINGS (T <sub>A</sub> = 25 °C unless otherwise noted)					
PARAMETER	SYMBOL	SE8D30D	SE8D30G	SE8D30J	UNIT
Device marking code		SD3D	SD3G	SD3J	
Maximum repetitive peak reverse voltage	$V_{RRM}$	200	400	600	V
Maximum average forward rectified current (fig.1)	I <sub>F(AV)</sub> (1)	3			А
	I <sub>F(AV)</sub> (2)	1.5			
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	40			А
Operating junction temperature range	T <sub>J</sub> <sup>(3)</sup>	-55 to +175			°C
Storage temperature range	T <sub>STG</sub>	-55 to +175			

#### Notes

- (1) Mounted on 30 mm x 30 mm pad areas aluminum PCB
- (2) Free air, mounted on recommended copper pad area
- (3) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta,JA}$

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<b>ELECTRICAL CHARACTERISTICS</b> (T <sub>J</sub> = 25 °C unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	- T <sub>J</sub> = 25 °C	V <sub>F</sub> <sup>(1)</sup>	0.91	-	V
	I <sub>F</sub> = 3 A			0.97	1.1	
	I <sub>F</sub> = 1.5 A	T <sub>J</sub> = 125 °C		0.79	-	
	I <sub>F</sub> = 3 A			0.86	0.98	
Reverse current	Rated V <sub>R</sub>	T <sub>J</sub> = 25 °C	I <sub>R</sub> <sup>(2)</sup>	-	10	
	nateu v <sub>R</sub>	T <sub>J</sub> = 125 °C		13	100	μΑ
Typical reverse recovery time	I <sub>F</sub> = 0.5 A, I <sub>R</sub> = 01 A, I <sub>rr</sub> = 0.25 A		t <sub>rr</sub>	1500	-	ns
Typical junction capacitance	4.0 V, 1 MHz		CJ	19	-	pF

#### Notes

 $^{(1)}\,$  Pulse test: 300  $\mu s$  pulse width, 1 % duty cycle

(2) Pulse test: pulse width ≤ 5 ms

THERMAL CHARACTERISTICS (T <sub>A</sub> = 25 °C unless otherwise specified)					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Typical thermal resistance	R <sub>0</sub> JA (1)(2)	120	150	°C/W	
	R <sub>0JM</sub> (3)	12	15	C/VV	

#### Notes

- (1) The heat generated must be less than the thermal conductivity from junction-to-ambient:  $dP_D/dT_J < 1/R_{\theta JA}$
- (2) Thermal resistance junction-to-ambient to follow JEDEC® 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint
- (3) Thermal resistance junction-to-mount to follow JEDEC 51-14 transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)						
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE		
SE8D30J-M3/H	0.033	Н	3500	7" diameter plastic tape and reel		
SE8D30J-M3/I	0.033	I	14 000	13" diameter plastic tape and reel		
SE8D30JHM3/H (1)	0.033	Н	3500	7" diameter plastic tape and reel		
SE8D30JHM3/I <sup>(1)</sup>	0.033	I	14 000	13" diameter plastic tape and reel		

### Note

(1) AEC-Q101 qualified

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### RATINGS AND CHARACTERISTICS CURVES (T<sub>A</sub> = 25 °C unless otherwise noted)

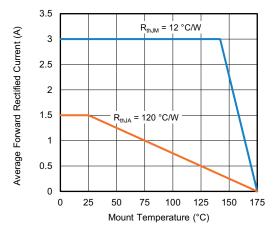


Fig. 1 - Maximum Forward Current Derating Curve

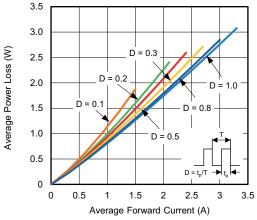


Fig. 2 - Forward Power Loss Characteristics

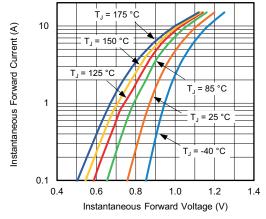


Fig. 3 - Typical Instantaneous Forward Characteristics

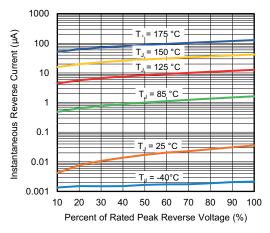


Fig. 4 - Typical Reverse Leakage Characteristics

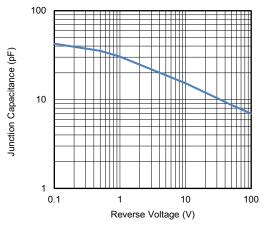


Fig. 5 - Typical Junction Capacitance

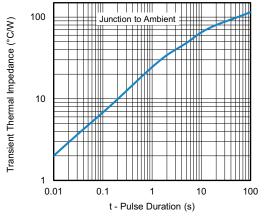


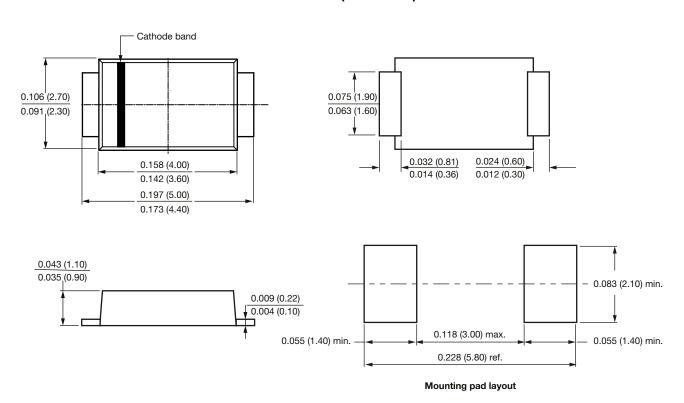
Fig. 6 - Typical Transient Thermal Impedance



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### **PACKAGE OUTLINE DIMENSIONS** in inches (millimeters)

### SlimSMAW (DO-221AD)





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